At page 15, line 17 through page 16, line 5, please delete the paragraph and substitute therefor:

To compress, the layer formed on the support is preferably subjected to a compressive force of at least 44 N/mm^2, more preferably at least 135 N/mm^2, most preferably at least 180 N/mm^2. Below 44 N/mm^2, the layer containing the fine conductive particles cannot be adequately compressed and it is difficult to obtain a highly conductive film. The higher the compressive force, the greater the strength of the coating and the higher the adhesion to the support. Speaking of the conductive film, it has better electrical continuity and the coating has higher strength while exhibiting stronger adhesion to the support. On the other hand, the higher the compressive force, the higher the pressure resistance that the apparatus is required to withstand. Considering these factors, the compressive force is generally recommended not to exceed 1000 N/mm^2. Compressing is preferably performed at temperatures near ordinary levels (15 - 40 °C). The compressing operation that can be performed at temperatures near ordinary levels is one of the salient advantages of the invention.

IN THE CLAIMS

Please amend Claims 1, 2, 8, and 9 as shown in clean form below:[2]

1. (Once Amended) A transparent conductive multi-layer structure, comprising:

a substrate overlaid with a support which in turn is overlaid with a conductive layer containing fine conductive particles, said multi-layer structure having a surface resistivity of 10 - 10^3 Ω/□ and a visible light transmittance of at least 70%.

2. (Once Amended) The transparent conductive multi-layer structure according to claim 1, wherein the fine conductive particles are the fine particles of indium-tin oxide.

[2] A marked-up copy of the claims is attached hereto.